

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	645	("hydrogen peroxide" or "H.sub.2O.sub.2") same slurry same Ph	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/25 06:56
L2	195	1 and CMP	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/25 08:11
L3	703	(CMP or "chemical mechanical polishing") same ("hydrogen peroxide" or "H.sub.2O.sub.2" or "ferric nitrate" or oxidizer) same (oxide or dielectric)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/25 08:12
L4	1319	(CMP or "chemical mechanical polishing") and ("hydrogen peroxide" or "H.sub.2O.sub.2" or "ferric nitrate" or oxidizers) and plug	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/25 08:14
L5	723	(CMP or "chemical mechanical polishing") and ("hydrogen peroxide" or "H.sub.2O.sub.2" or "ferric nitrate" or oxidizers) and plug and gate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/25 08:14
L6	229	(CMP or "chemical mechanical polishing") and slurry and plug and gate and spacers and polysilicon	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/25 08:15
L7	35	"hard mask" and slurry and plug and gate and spacers and polysilicon and polish\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/25 08:16
L8	191	("hard mask" or mask\$4) and slurry and plug and gate and spacers and polysilicon and polish\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/25 08:16
L9	2	"6334880".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/25 08:17
L10	2	"6607955".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/25 08:23

L12	5	kwon-pan-ki.in.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/25 08:35
L13	18	lee-sang-ick.in.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/25 08:35